PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3992130

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
XINZHE JIN	07/21/2016
HIDEAKI MAEDA	07/21/2016
YOSHINORI YANAGISAWA	07/21/2016

RECEIVING PARTY DATA

Name:	RIKEN
Street Address:	2-1 HIROSAWA, WAKO-SHI
City:	SAITAMA
State/Country:	JAPAN
Postal Code:	351-0198

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15116432

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SIGNATURE:	/Paige Alsbury/
DATE SIGNED:	08/04/2016

Total Attachments: 2
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ASSIGNMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, the person(s) named below (referred to as "INVENTOR" whether singular or plural) has sold, assigned, and transferred and does hereby sell, assign, and transfer to **RIKEN**, a corporation of JAPAN, having a place of business at **2-1 Hirosawa, Wako-shi, Saitama 351-0198, Japan** ("ASSIGNEE"), for itself and its successors, transferees, and assignees, the following:

1. The entire worldwide right, title, and interest in all inventions and improvements ("SUBJECT MATTER") that are disclosed in the provisional application filed under 35 U.S.C. §111(b) or non-provisional application filed under 35 U.S.C. §111(a) and entitled **LOW-RESISTANCE CONNECTION BODY FOR HIGH-TEMPERATURE SUPERCONDUCTING WIRE MATERIAL AND CONNECTION METHOD** ("APPLICATION"), which:

☒ having a filing date of August 3, 2016, and bearing U.S. application serial number 15/116,432.

☒ The APPLICATION claims the benefit of an international application, filed on October 21, 2014, bearing international application serial number PCT/JP2014/077966.

2. The entire worldwide right, title, and interest in and to: (a) the APPLICATION; (b) all applications claiming priority from the APPLICATION; (c) all provisional, utility, divisional, continuation, substitute, renewal, reissue, and other applications related thereto which have been or may be filed in the United States or elsewhere in the world; (d) all patents (including reissues and re-examinations) which may be granted on the applications set forth in (a), (b), and (c) above; and (e) all right of priority in the APPLICATION and in any underlying provisional or foreign application, together with all rights to recover damages for infringement of provisional rights.

INVENTOR agrees that ASSIGNEE may apply for and receive patents for SUBJECT MATTER in ASSIGNEE's own name.

INVENTOR agrees to do the following, when requested, and without further consideration, in order to carry out the intent of this Assignment: (1) execute all oaths, assignments, powers of attorney, applications, and other papers necessary or desirable to fully secure to ASSIGNEE the rights, titles and interests herein conveyed; (2) communicate to ASSIGNEE all known facts relating to the SUBJECT MATTER; and (3) generally do all lawful acts that ASSIGNEE shall consider desirable for securing, maintaining, and enforcing worldwide patent protection relating to the SUBJECT MATTER and for vesting in ASSIGNEE the rights, titles, and interests herein conveyed. INVENTOR further agrees to provide any successor, assign, or legal representative of ASSIGNEE with the benefits and assistance provided to ASSIGNEE hereunder.

Title: LOW-RESISTANCE CONNECTION BODY FOR HIGH-TEMPERATURE SUPERCONDUCTING WIRE MATERIAL AND CONNECTION METHOD
Filed:
Application No.:

INVENTOR represents that INVENTOR has the rights, titles, and interests to convey as set forth herein, and covenants with ASSIGNEE that the INVENTOR has not made and will not hereafter make any assignment, grant, mortgage, license, or other agreement affecting the rights, titles, and interests herein conveyed.

INVENTOR grants the attorney of record the power to insert on this Assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

This Assignment may be executed in one or more counterparts, each of which shall be deemed an original and all of which may be taken together as one and the same Assignment.

x Xinzhe Jin — 7/21/2016
Xinzhe Jin — Date of Signature

x Hideaki Maeda — 7/21/2016
Hideaki Maeda — Date of Signature

x Yoshinori Yanagisawa — 7 / 21 / 2016
Yoshinori Yanagisawa — Date of Signature